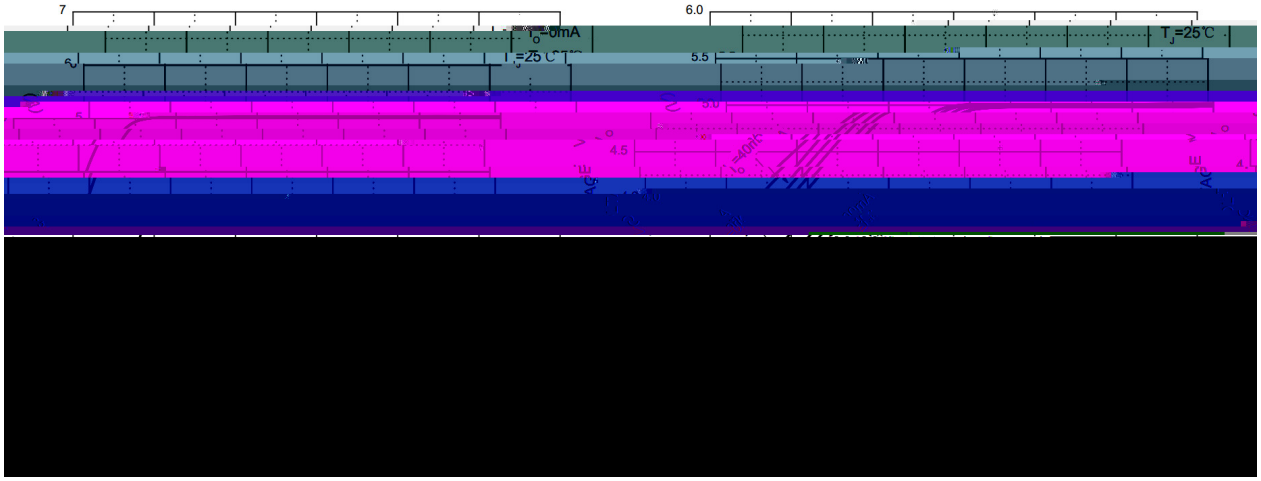
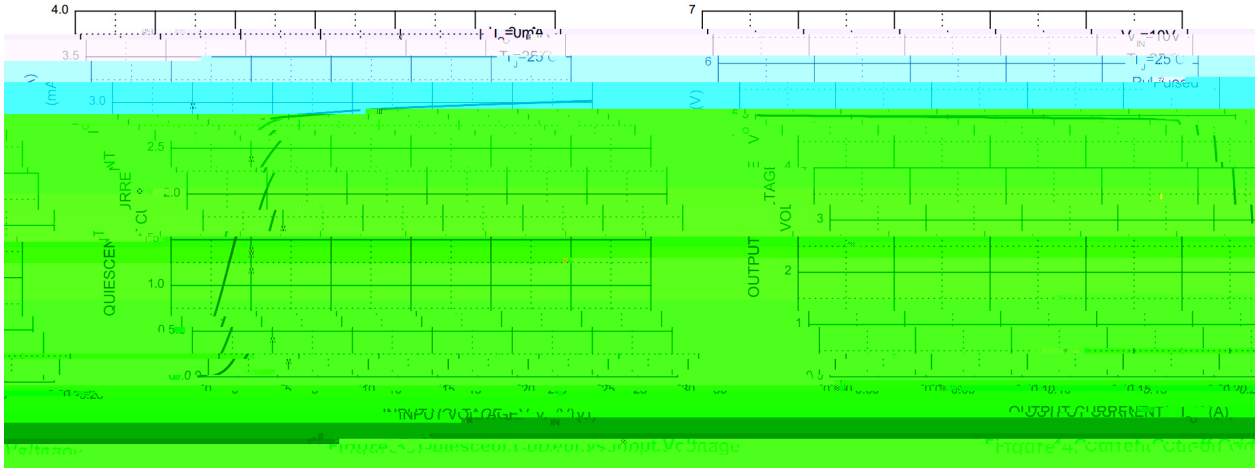
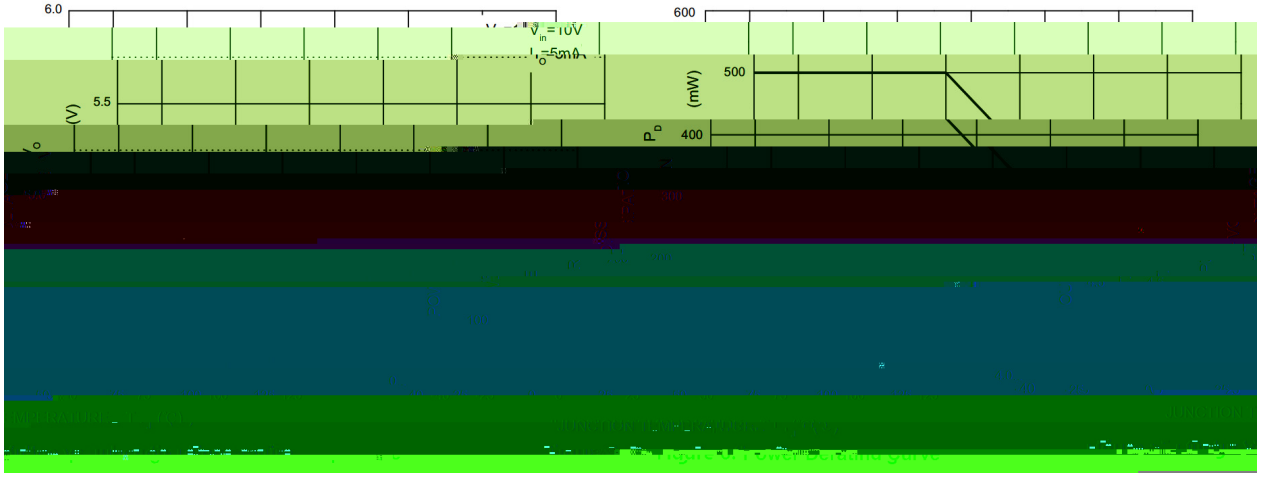
Parameter	Symbol	Rating	Unit
Input voltage	V_I	36	V
Output current(V_I=8V)	I_O	100	mA
Operating virtual Junction temperature	T_J	0 125	
Power Dissipation	P_D	500	mW
Storage temperature range	T_{stg}	-65 150	
Thermal resistance junction-ambient	R_{JA}	200	/W

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Output voltage	V_O	I_o 40mA T_j=25	4.80	5.0	5.2	V
		I_O=1mA to 40mA V_I=7V to 20V	4.75	5.0	5.25	V
		I_O=1mA to 70mA V_I=10V	4.75	5.0	5.25	V
Input regulation	Vo	V_I=7V to 20V T_j=25		32	150	mV

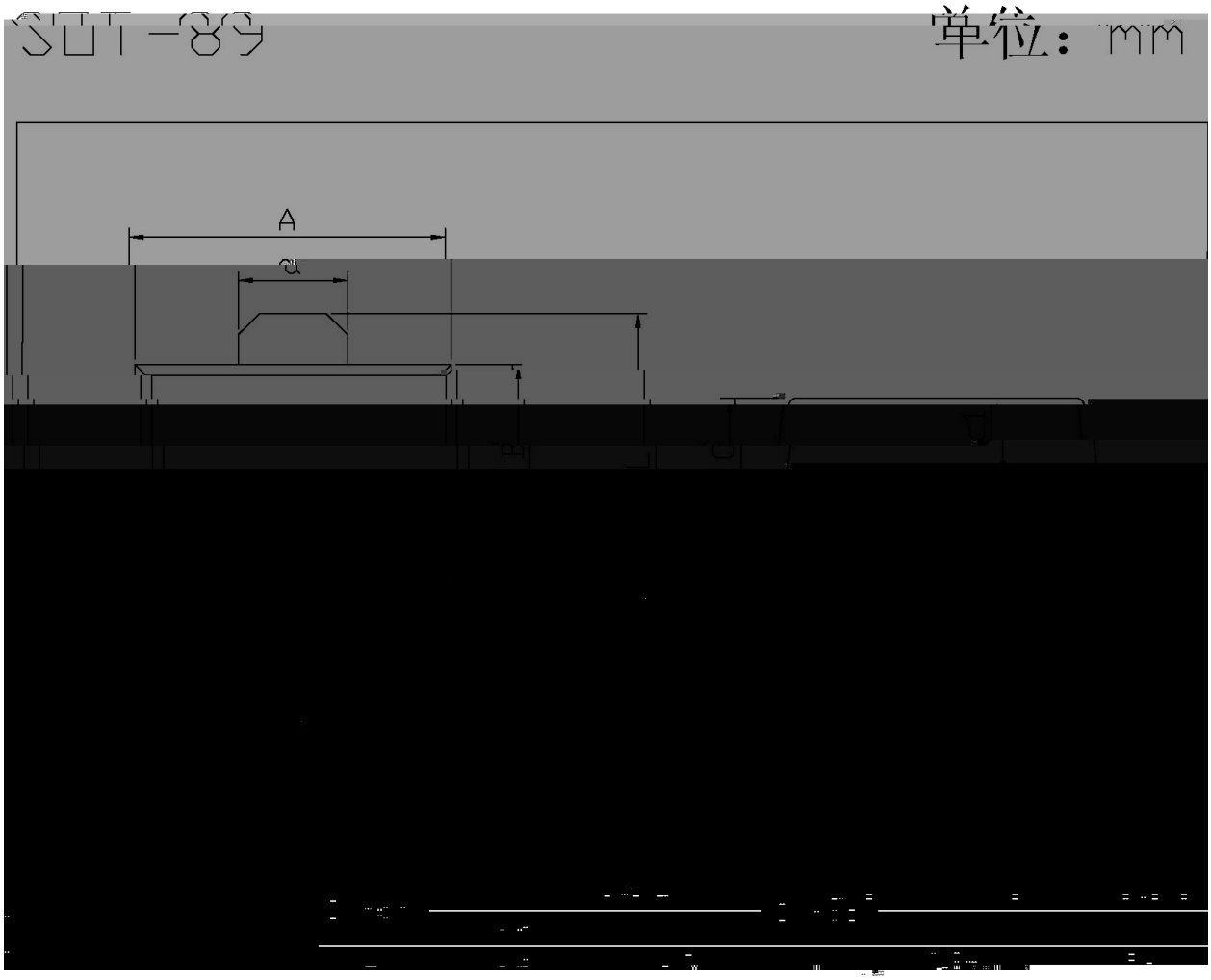
/ Electrical Characteristic Curve



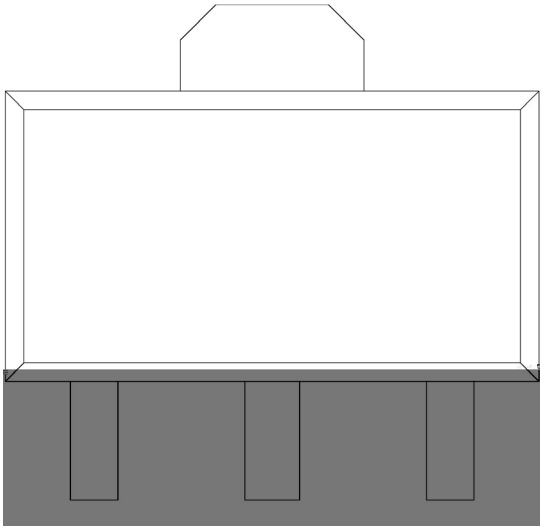




/ Package Dimensions



/ Marking Instructions



H

L05

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

		Note:
1	150 180 60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2	245 5 5 0.5sec;	2.Peak Temp.:245 5 , Duration:5 0.5sec.
3	2 10 /sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260 5	10 1 sec.	Temp.:260±5	Time:10±1 sec

[redacted]

/ REEL

Package Type	Units	Dimension	(unit mm³)